

Material Declaration Report

Package Type:	FQFP 128L
Pericom Package Code:	MA128(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
REACH Compliance:	Yes
Halogen Free:	Yes

Component Weight (mg):	1718.000
Termination Plating:	matte Sn
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	3
Peak Body Temp (C):	245
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	6/18/2010

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)			
MOLD COMPOUND	1162.206	ASE	Silica Fused	60676-86-0	88.000	1022.741			
			Epoxy Resin	Proprietary	5.000	58.110			
			Epoxy, Cresol Novolac	29690-82-2	2.000	23.244			
			Phenolic Resin	Proprietary	4.500	52.299			
			Carbon Black	1333-86-4	0.500	5.811			
		GTK	Epoxy Resin	Trade secret	5.000	58.110			
			Epoxy, Cresol Novolac	29690-82-2	2.500	29.055			
			Phenol Resin	Trade secret	5.000	58.110			
			Carbon Black	1333-86-4	0.500	5.811			
			Silica fused	60676-86-0	81.000	941.387			
LEADFRAME	460.424		Copper	7440-50-8	95.140	438.047			
			Magnesium	7440-02-0	3.200	14.734			
			Nickel	7440-22-4	0.760	3.499			
SILICON DIE	31.603		Silicon	7440-21-3	99.192	31.348			
			Non-hazardous Metal	Proprietary	0.808	0.255			
			DIE ATTACH EPOXY	7.171	ASE	Silver	7440-22-4	84.000	6.024
						Epoxy Resin	Proprietary	8.000	0.574
DIE ATTACH EPOXY	7.171	GTK	gamma-Butyrolactone	96-48-0	8.000	0.574			
			Silver	7440-22-4	67.000	4.805			
			Epoxy Resin	proprietary	15.000	1.076			
			Aliphatic anhydride	proprietary	8.000	0.574			
			2-Butoxyethyl acetate	112-07-2	5.000	0.359			
GOLD WIRE	5.056		Polymeric material	proprietary	5.000	0.359			
			Gold(Au)	7440-57-5	99.990	5.055			
SOLDER PLATING	51.540		Impurities	-	0.010	0.001			
			Tin (Sn)	7440-31-5	99.990	51.535			
SOLDER PLATING	51.540		Impurities	-	0.010	0.005			

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device						
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
		<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
		O	O	O	O	O	O
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.</p> <p>X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>							